NEWS RELEASE

Christina Sanchez or Beth Smith
The Simon Group
Phone: (215) 453-8700
Fax: (215) 453-1670
E-mail: publicrelations@simongroup.com

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New CSP Test Socket for Smaller Devices Up to 13 mm Squared Joins Aries' Family of Sockets Featuring Adjustable Pressure Pad

Bristol, Pa. August 2009 – Aries Electronics, an international manufacturer of standard, programmed and custom interconnection products, has expanded its line of CSP (chip scale package)/MicroBGA (ball grid array) test and burn-in sockets with an optional adjustable pressure pad to include a version that accommodates devices 13 mm squared or smaller, with a pitch of 0.30 mm or higher.

The new CSP socket incorporates a simplified pressure pad compression design for a greater range of movement without over compressing the device. This makes the new socket ideal for testing very small and/or fragile devices without doing damage. Users no longer have to compromise the socket footprint for the ease of adjustability.

The pressure pad on the new socket for devices up to 13 mm squared is easily adjustable with the lid open or closed simply by using the included hex key, and can easily handle device thickness variations up to 1 mm. Greater ranges can be custom-designed per application.

The ability to adjust the compression force on the device enables the operator to fine tune the pressure pad force and achieve a perfect connection. This is helpful when trying to overcome co-planarity issues with the device or test board. Previously, any device that

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ARI-A-7447

differed considerably in thickness would have required multiple test sockets. The new adjustable socket not only saves time but also money.

The Aries CSP/MicroBGA test and burn-in socket family accommodates a variety of CSP, MicroBGA, DSP, LGA, SRAM, DRAM and Flash drives by using machined (for small quantities) or custom molded (for large quantities) pressure pads and interposers.

With a signal path of only 0.077 inches (1.96 mm), the new CSP/MicroBGA socket for devices up to 13 mm squared provides minimal signal loss for higher bandwidth capability. The cost-efficient socket is easily mounted and removed to and from the BIB (burn-in-board), due to solderless pressure mount compression spring probes precisely located by two molded plastic alignment pins and mounted with four stainless steel screws. In addition, the socket's small overall size allows the maximum number of sockets per BIB and BIBs per oven, while remaining operator friendly.

Compression spring probes are constructed of heat-treated beryllium-copper, and plated with a minimum of 30 micro inches (0.75 micro mm) gold per MIL-G-45204 over a minimum of 30 micro inches (0.75 micro mm) nickel per SAE-AMS-QQ-N-290.

Contact forces are 15 g per contact on a 0.30 mm to 0.35 mm pitch; 16 g per contact on a 0.40 mm to 0.45 mm pitch and 25 g per contact on pitches of 0.50 mm or larger. Operating temperature is -55°C to +150°C (-67°F to +302°F) and estimated contact life is a minimum of 500,000 cycles.

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ARI-A-7447

Molded components are UL94V-0 Ultem, while machined components are UL94V-0 PEEK or Torlon. All hardware is stainless steel.

As with all Aries sockets, the new CSP/MicroBGA test and burn-in socket is available in custom materials, platings, sizes and configurations to suit specific customer applications.

Pricing for a typical BGA device with 64 leads on 0.8mm pitch starts at $200 per socket. Delivery is four to six weeks ARO.

For additional information, contact Aries Electronics Inc., 2609 Bartram Road, Bristol, Pa. 19007-6810; Tel: 215-781-9956; Fax: 215-781-9845; Email: info@arieselec.com; Web: http://www.arieselec.com, Data sheet #23017-http://www.arieselec.com/Web_Data_Sheets/23017/23017.htm, Europe Email: europe@arieselec.com.

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ARI-A-7447

READER SERVICE INQUIRIES: Please forward all reader service inquiries to Frank Folmsbee, Aries Electronics Inc., 2609 Bartram Road, Bristol, Pa. 19007-6810.

EDITORS NOTE: Headquartered in Bristol, Pa., Aries Electronics Inc. manufactures an extremely broad range of custom and standard interconnection and packaging products for electronics. Industry leading products include Zero Insertion Force (ZIF) test sockets for DIP, PGA, PLCC and SOIC devices; the "intelligent" Correct-A-Chip™ product line; adapters and connectors; several patented concepts for BGA (ball grid array) and LGA (land grid array) sockets; and an extensive array of high frequency test and burn in sockets. The company also specializes in meeting custom requirements for its customers.